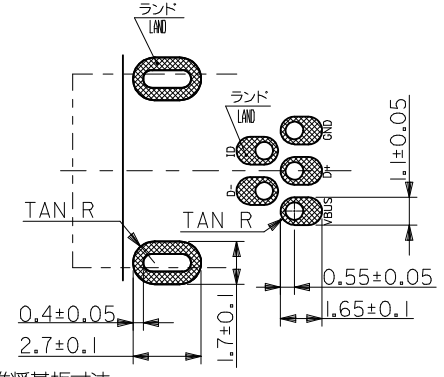
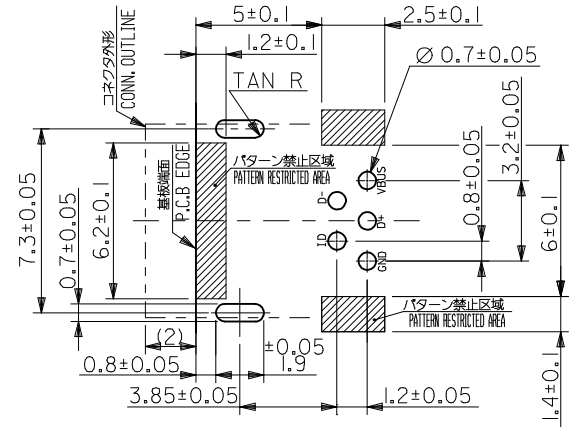
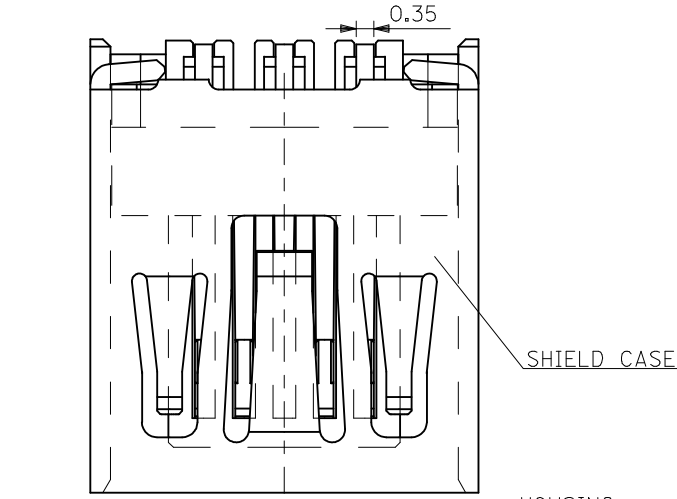
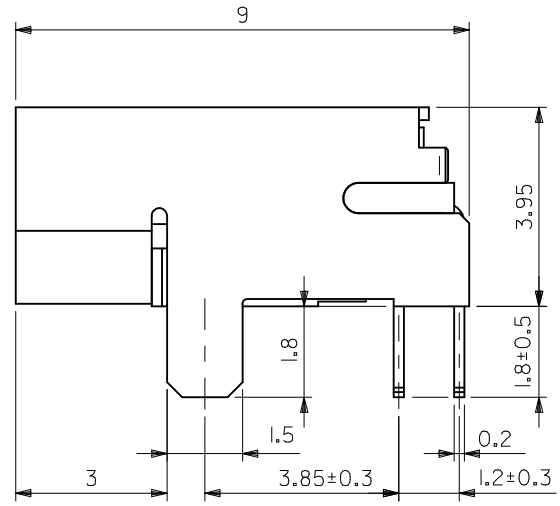
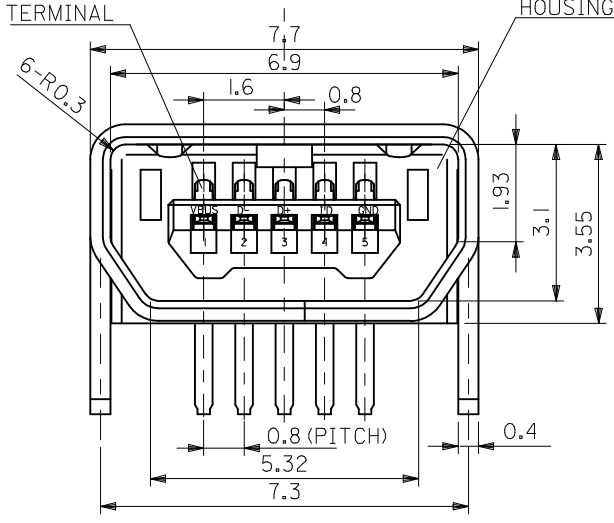


コネクタ実装側 (CONNECTOR MOUNT SIDE)

逆側 (REVERSE SIDE)



推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT



注記 1. 材質
NOTES MATERIAL

ハウジング: PA, ガラス充填, 灰色, UL94V-0
HOUSING: PA, GLASS FILLED, GRAY, UL94V-0
ターミナル: 銅合金 (t=0.2)
TERMINAL: COPPER ALLOY (t=0.2)
シールド ケース: 銅合金 (t=0.4)
SHIELD CASE: COPPER ALLOY (t=0.4)

2. メッキ仕様
PLATING

ターミナル
TERMINAL
接点部: 金メッキ 0.76MICRO METER MIN.
CONTACT AREA: GOLD 0.76MICRO METER MIN.
半田付け部: 銅メッキ 1.0MICRO METER MIN.
SOLDER TAIL AREA: TIN 1.0MICRO METER MIN.
下地部: ニッケルメッキ 4.0MICRO METER MIN.
UNDER PLATING: NICKEL 4.0MICRO METER MIN.
シールド ケース
SHIELD CASE
: 銅メッキ 1.0MICRO METER MIN.
: TIN 1.0MICRO METER MIN.
下地部: ニッケルメッキ 1.0MICRO METER MIN.
UNDER PLATING: NICKEL 1.0MICRO METER MIN.

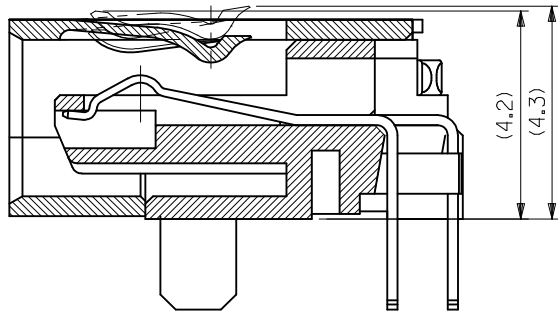
3. 本製品は56579-0511の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 56579-0511

56579-0519
TRAY PKG.
ORDER NO.

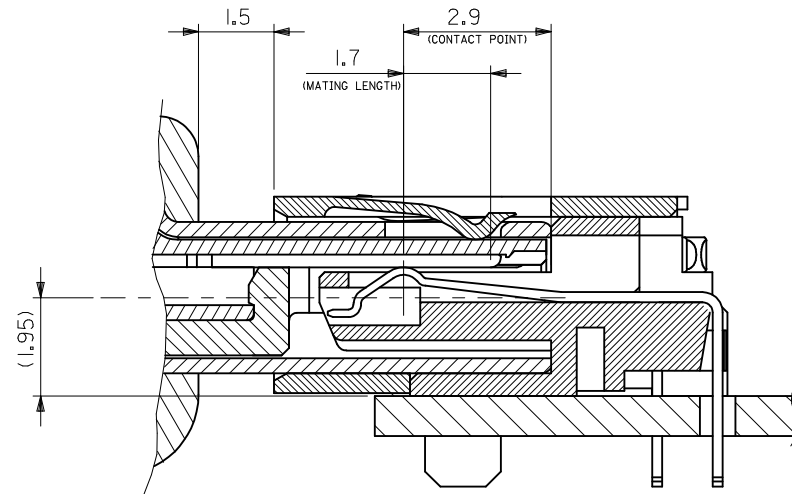
MODEL No.56579-***19

REVISED EC NO: J2009-1533 DRW: NESATO 2009/06/25 CHKD: MATSUMOTO 2009/06/25 APPR: NUKITA 2009/06/25 REV: A	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		DRAWN BY M. NAGATA	DATE 2004/03/10	TITLE USB SERIES MINI-AB REC.ASS'Y DIP -LEAD FREE-			
		CHECKED BY K. TOJO	DATE 2004/03/10	MOLEX INCORPORATED			
		APPROVED BY M. SASAO	DATE 2004/03/10	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-56579-014	SHEET NO. 1 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1



SECTION



MATING

MODEL No.56579-**19

REVISED EC NO: J2009-1533 DRW: NESATO 2009/06/25 CHK: D: MATSUMOTO 2009/06/25 APPR: NUKITA 2009/06/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	DRAWN BY M. NAGATA	DATE 2004/03/10	TITLE USB SERIES MINI-AB REC. HS'G ASS'Y (DIP) -LEAD FREE-		
	30 OVER ±0.3	ANGULAR ±3 °	CHECKED BY K. TOJO	DATE 2004/03/10	MOLEX INCORPORATED		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY M. SASAO	DATE 2004/03/10	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-56579-014	SHEET NO. 2 OF 2